

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Daniel YAP) Re: Information Disclosure
) Statement
Serial No.: not yet assigned)
Filed: concurrently herewith) Group: not yet assigned
)
Divisional of USSN <u>10/116,800</u>) Examiner: not yet assigned
filed on <u>April 5, 2002</u>)
)
For: "WAVEGUIDE-BONDED) Our Ref: B-4246DIV 621598-8
OPTOELECTRONIC DEVICES")
) Date: February 3, 2004

MAIL STOP PATENT APPLICATION
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with the Applicant's duty to disclose information which may be material to the examination of this application, the undersigned respectfully requests that the documents cited by the Examiner and/or submitted by the Applicant in connection with U.S. Serial No. 10/116,800 filed on April 5, 2002 (the parent of the Applicants' subject application) be considered by the Examiner before issuing the first Office Action on the merits.

For the Examiner's convenience, Form PTO-1449 (modified) is enclosed herewith listing the documents cited by the Examiner and/or submitted by the Applicant in connection with U.S. Serial No. 10/116,800.

The filing of this Information Disclosure Statement (IDS) shall not be construed as a representation that a search has been made (37 C.F.R. 1.97(g)), an admission that the information cited is, or is considered to be, material to patentability, or that no other material information exists.

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If any fees are due, please charge our Deposit Account No. 12-0415 or credit any overpayment to our Account No. 12-0415. No fees should be due because this Information Disclosure Statement is being filed concurrently with the above-identified U.S. patent application.

The filing of this Information Disclosure Statement shall not be construed as an admission against interest in any manner. (Notice of January 9, 1992, 1135 O.G. 13-25, at 25.)

The person making this statement is the practitioner who signs below on the basis of information supplied by an individual associated with the filing and prosecution of this application (37 C.F.R. § 1.56(c)) and on the basis of information in the practitioner's file.

Respectfully submitted,



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Enclosures: Form PTO-1449 (modified) (2 pages)

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Form PTO-1449 (Modified)	ATTY DOCKET NO. B-4246DIV 621598-8	U.S. SERIAL NO. not yet assigned
LIST OF PATENTS AND PUBLICATIONS STATEMENT	APPLICANT(S) Daniel YAP	
	FILING DATE concurrently herewith	GROUP 2811

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	ISSUE DATE	NAME	CLASS	SUBCLASS	FILING DATE or 102(e) DATE IF APPROPRIATE
	5,625,729	4/1997	Brown	385	31	

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	PUBLICATION DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES/NO
99/66613	12/1999	WO			
01/29992	4/2001	WO			

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	Alexe, M., et al., "Low Temperature GaAs/Si Direct Wafer Bonding," <i>Electronics Letters</i> , Vol. 36, No. 7 (March 30, 2000).
	Chu, S.T., et al., "Wavelength Trimming of a Microring Resonator Filter by Means of a UV Sensitive Polymer Overlay," <i>IEEE Photonics Technology Letters</i> , Vol. 11, No. 6, pp 688-690 (June 1999).
	Corbett, B., et al., "Low-Threshold Lasing in Novel Microdisk Geometries," <i>IEEE Photonics Technology Letters</i> , Vol. 8, No. 7, pp 855-857 (July 1996).
	Corbett, B., "Spectral Characteristics of Low Threshold Microdisks," <i>IEEE Lasers and Electro-Optics Society 1996 Annual Meeting</i> , Vol. 2, pp 197-198 (1996).
	Hansen, D.M., et al., "Development of a Glass-Bonded Compliant Substrate", <i>Journal of Crystal Growth</i> , Vol. 195, pp. 144-150 (1998).
	Kato, D., et al., "PLC Hybrid Integration Technology and Its Application to Photonic Components", <i>IEEE Journal of Selected Topics in Quantum Electronics</i> , Vol. 6, No. 1, pp. 4-13 (2000).

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	Little, B.E., et al., "Ultra-Compact Si-SiO ₂ Microring Resonator Optical Channel Dropping Filters," <i>IEEE Photonics Technology Letters</i> , Vol. 10, No. 4, pp 549-551 (April 1998).
	Little, B.E., et al., "Wavelength Switching and Routing Using Absorption and Resonance", <i>IEEE Photonics Technology Letters</i> , Vol. 10, No. 6, pp 816-818 (June 1998).
	London, Joanna M., et al., "Preparation of Silicon-on-Gallium Arsenide Wafers for Monolithic Optoelectronic Integration", <i>IEEE Photonics Technology Letters</i> , Vol. 11, No. 8, pp. 958-960 (1999).
	MacDonald, R.I., et al., "Hybrid Optoelectronic Integrated Circuit," <i>Applied Optics</i> , Vol. 26, No. 5, pp 842-844 (March 1, 1987).
	Narayanan, A., et al., "High-Efficiency Waveguide-Coupled $\lambda=1.3 \mu\text{m}$ In _x Ga _{1-x} As/GaAs MSM Detector Exhibiting Large Extinction Ratios at L and X Band", <i>IEEE Photonics Technology Letters</i> , Vol. 5, No. 5, pp. 514-517 (1993).
	Sakamoto, S.R., et al., "Substrate Removed GaAs-AlGaAs Electrooptic Modulators", <i>IEEE Photonics Technology Letters</i> , Vol. 11, No. 10, pp. 1244-1246 (1999).
	Tishinin, D.V., et al., "Vertical Resonant Couplers with Precise Coupling Efficiency Control Fabricated by Wafer Bonding", <i>IEEE Photonics Technology Letters</i> , Vol. 11, No. 8, pp. 1003-1005 (1999).
	Yanagisawa, M., et al., "Film-Level Hybrid Integration of AlGaAs Laser Diode with Glass Waveguide on Si Substrate," <i>IEEE Photonics Technology Letters</i> , Vol. 4, No. 1, pp 21-23 (January 1992).
	Yi-Yan, A., et al., "GaInAs/InP pin Photodetectors Integrated with Glass Waveguides," <i>Electronics Letters</i> , Vol. 27, No. 1, pp 87-89 (January 3, 1991).

EXAMINER	DATE CONSIDERED

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.